74HC132; 74HCT132

Quad 2-input NAND Schmitt trigger Rev. 4 — 1 December 2015

Product data sheet

1. **General description**

The 74HC132; 74HCT132 is a quad 2-input NAND gate with Schmitt-trigger inputs. Inputs include clamp diodes. This enables the use of current limiting resistors to interface inputs to voltages in excess of V_{CC}. Schmitt trigger inputs transform slowly changing input signals into sharply defined jitter-free output signals.

2. Features and benefits

- Complies with JEDEC standard no. 7A
- ESD protection:
 - ◆ HBM JESD22-A114F exceeds 2000 V
 - MM JESD22-A115-A exceeds 200 V
- Multiple package options
- Specified from -40 °C to +85 °C and from -40 °C to +125 °C

Applications

- Wave and pulse shapers
- Astable multivibrators
- Monostable multivibrators

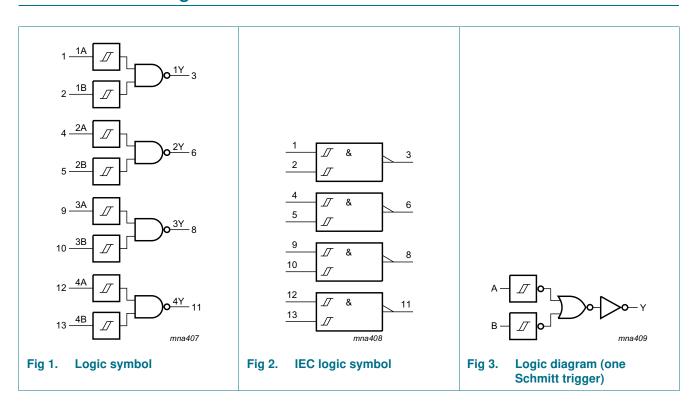


4. Ordering information

Table 1. Ordering information

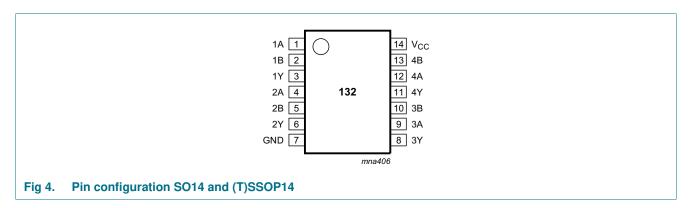
Type number	Package											
	Temperature range	Name	Description	Version								
74HC132D	-40 °C to +125 °C	SO14	plastic small outline package; 14 leads; body width	SOT108-1								
74HCT132D			3.9 mm									
74HC132DB	-40 °C to +125 °C	SSOP14	plastic shrink small outline package; 14 leads; body	SOT337-1								
74HCT132DB			width 5.3 mm									
74HC132PW	-40 °C to +125 °C	TSSOP14	plastic thin shrink small outline package; 14 leads;	SOT402-1								
74HCT132PW			body width 4.4 mm									

5. Functional diagram



6. Pinning information

6.1 Pinning



6.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
1A to 4A	1, 4, 9, 12	data input
1B to 4B	2, 5, 10, 13	data input
1Y to 4Y	3, 6, 8, 11	data output
GND	7	ground (0 V)
V _{CC}	14	supply voltage

7. Functional description

Table 3. Function table [1]

Input		Output
nA	nB	nY
L	L	Н
L	Н	Н
Н	L	Н
Н	Н	L

[1] H = HIGH voltage level; L = LOW voltage level; X = don't care.

8. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions		Min	Max	Unit
V _{CC}	supply voltage			-0.5	+7	V
I _{IK}	input clamping current	$V_{I} < -0.5 \text{ V or } V_{I} > V_{CC} + 0.5 \text{ V}$	[1]	-	±20	mA
I _{OK}	output clamping current	$V_O < -0.5 \text{ V or } V_O > V_{CC} + 0.5 \text{ V}$	[1]	-	±20	mA
Io	output current	$-0.5 \text{ V} < \text{V}_{\text{O}} < \text{V}_{\text{CC}} + 0.5 \text{ V}$		-	±25	mA
I _{CC}	supply current			-	50	mA
I _{GND}	ground current			-50	-	mA
T _{stg}	storage temperature			-65	+150	°C
P _{tot}	total power dissipation	SO14, and (T)SSOP14 packages	[2]	-	500	mW

^[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

9. Recommended operating conditions

Table 5. Recommended operating conditions

Voltages are referenced to GND (ground = 0 V)

Symbol	Parameter	Conditions	-	74HC132	2	7	Unit		
			Min	Тур	Max	Min	Тур	Max	
V_{CC}	supply voltage		2.0	5.0	6.0	4.5	5.0	5.5	V
VI	input voltage		0	-	V _{CC}	0	-	V_{CC}	٧
V _O	output voltage		0	-	V _{CC}	0	-	V_{CC}	٧
T _{amb}	ambient temperature		-40	+25	+125	-40	+25	+125	°C

^[2] For SO14 package: P_{tot} derates linearly with 8 mW/K above 70 °C. For (T)SSOP14 packages: P_{tot} derates linearly with 5.5 mW/K above 60 °C.

10. Static characteristics

Table 6. Static characteristics

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions		25 °C		-40 °C t	o +85 °C	-40 °C t	o +125 °C	Unit
			Min	Тур	Max	Min	Max	Min	Max	
74HC13	2									
V _{OH}	HIGH-level	$V_I = V_{T+}$ or V_{T-}								
	output voltage	$I_{O} = -20 \mu A$; $V_{CC} = 2.0 \text{ V}$	1.9	2.0	-	1.9	-	1.9	-	V
		$I_O = -20 \mu A$; $V_{CC} = 4.5 \text{ V}$	4.4	4.5	-	4.4	-	4.4	-	V
		$I_O = -20 \mu A$; $V_{CC} = 6.0 \text{ V}$	5.9	6.0	-	5.9	-	5.9	-	V
		$I_O = -4.0 \text{ mA}; V_{CC} = 4.5 \text{ V}$	3.98	4.32	-	3.84	-	3.7	-	V
		$I_{O} = -5.2 \text{ mA}; V_{CC} = 6.0 \text{ V}$	5.48	5.81	-	5.34	-	5.2	-	V
V _{OL}	LOW-level	$V_I = V_{T+}$ or V_{T-}								
	output voltage	$I_O = 20 \mu A; V_{CC} = 2.0 V$	-	0	0.1	-	0.1	-	0.1	V
		$I_O = 20 \mu A; V_{CC} = 4.5 V$	-	0	0.1	-	0.1	-	0.1	V
		$I_O = 20 \mu A; V_{CC} = 6.0 V$	-	0	0.1	-	0.1	-	0.1	V
		$I_O = 4.0 \text{ mA}; V_{CC} = 4.5 \text{ V}$	-	0.15	0.26	-	0.33	-	0.4	V
		$I_O = 5.2 \text{ mA}; V_{CC} = 6.0 \text{ V}$	-	0.16	0.26	-	0.33	-	0.4	V
I _I	input leakage current	$V_I = V_{CC}$ or GND; $V_{CC} = 6.0 \text{ V}$	-	-	±0.1	-	±1.0	-	±1.0	μΑ
I _{CC}	supply current	$V_I = V_{CC}$ or GND; $I_O = 0$ A; $V_{CC} = 6.0 \text{ V}$	-	-	2.0	-	20	-	40	μΑ
Cı	input capacitance		-	3.5	-	-	-	-	-	pF
74HCT1	32									
V _{OH}	HIGH-level	$V_{I} = V_{T+}$ or V_{T-} ; $V_{CC} = 4.5 \text{ V}$								
.	output voltage	I _O = -20 μA	4.4	4.5	-	4.4	-	4.4	-	V
		$I_{O} = -4.0 \text{ mA}$	3.98	4.32	-	3.84	-	3.7	-	V
V _{OL}	LOW-level	$V_{I} = V_{T+}$ or V_{T-} ; $V_{CC} = 4.5 \text{ V}$								
	output voltage	I _O = 20 μA;	-	0	0.1	-	0.1	-	0.1	V
		I _O = 4.0 mA;	-	0.15	0.26	-	0.33	-	0.4	V
l _l	input leakage current	$V_I = V_{CC}$ or GND; $V_{CC} = 5.5 \text{ V}$	-	-	±0.1	-	±1.0	-	±1.0	μА
I _{CC}	supply current	V _I = V _{CC} or GND; I _O = 0 A; V _{CC} = 5.5 V	-	-	2.0	-	20	-	40	μА
Δl _{CC}	additional supply current	per input pin; $V_I = V_{CC} - 2.1 \text{ V}; I_O = 0 \text{ A};$ other inputs at V_{CC} or GND; $V_{CC} = 4.5 \text{ V}$ to 5.5 V	-	30	108	-	135	-	147	μА
Cı	input capacitance		-	3.5	-	-	-	-	-	pF

11. Dynamic characteristics

Table 7. Dynamic characteristics

 $GND = 0 \ V; \ C_L = 50 \ pF;$ for load circuit see Figure 6.

Symbol	Parameter	Conditions			25 °C		-40 °C to	+125 °C	Unit
			Min	Тур	Max	Max (85 °C)	Max (125 °C)		
74HC132	2							-	
t _{pd} propagation delay nA, nB to nY; see Figure 5		[1]							
		V _{CC} = 2.0 V		-	36	125	155	190	ns
		V _{CC} = 4.5 V		-	13	25	31	38	ns
$V_{CC} = 5.0 \text{ V}; C_L = 15 \text{ pF}$			-	11	-	-	-	ns	
	V _{CC} = 6.0 V			-	10	21	26	32	ns
t _t	transition time	see Figure 5	[2]						
		V _{CC} = 2.0 V		-	19	75	95	110	ns
		V _{CC} = 4.5 V		-	7	15	19	22	ns
		V _{CC} = 6.0 V		-	6	13	16	19	ns
C_{PD}	power dissipation capacitance	per package; $V_I = GND$ to V_{CC}	[3]	-	24	-	-	-	pF
74HCT13	32	-			-	-	-	+	+
t _{pd}	propagation delay	nA, nB to nY; see Figure 5	<u>[1]</u>						
		V _{CC} = 4.5 V		-	20	33	41	50	ns
		$V_{CC} = 5.0 \text{ V}; C_L = 15 \text{ pF}$		-	17	-	-	-	ns
t _t	transition time	V _{CC} = 4.5 V; see <u>Figure 5</u>	[2]	-	7	15	19	22	ns
C_{PD} power dissipation per package; $V_{I} = \text{GND to } V_{CC} - 1.5 \text{ V}$		[3]	-	20	-	-	-	pF	

^[1] t_{pd} is the same as t_{PHL} and t_{PLH} .

$$P_D = C_{PD} \times V_{CC}{}^2 \times f_i \times N + \sum{(C_L \times V_{CC}{}^2 \times f_o)}$$
 where:

 f_i = input frequency in MHz;

f_o = output frequency in MHz;

C_L = output load capacitance in pF;

 V_{CC} = supply voltage in V;

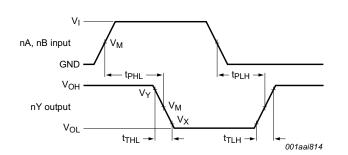
N = number of inputs switching;

 $\sum (C_L \times V_{CC}^2 \times f_o) = \text{sum of outputs.}$

^[2] t_t is the same as t_{THL} and t_{TLH} .

^[3] C_{PD} is used to determine the dynamic power dissipation (P_D in μW):

12. Waveforms



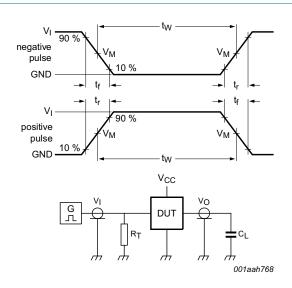
Measurement points are given in Table 8.

 $\ensuremath{V_{OL}}$ and $\ensuremath{V_{OH}}$ are typical voltage output levels that occur with the output load.

Fig 5. Input to output propagation delays

Table 8. Measurement points

Туре	Input	Output		
	V _M	V _M	V _X	V _Y
74HC132	0.5V _{CC}	0.5V _{CC}	0.1V _{CC}	0.9V _{CC}
74HCT132	1.3 V	1.3 V	0.1V _{CC}	0.9V _{CC}



Test data is given in Table 9.

Definitions test circuit:

 R_{T} = termination resistance should be equal to output impedance $Z_{\text{\scriptsize 0}}$ of the pulse generator.

C_L = load capacitance including jig and probe capacitance.

Fig 6. Test circuit for measuring switching times

Table 9. Test data

Туре	Input		Load	Test
	VI	t _r , t _f	CL	
74HC132	V _{CC}	6.0 ns	15 pF, 50 pF	t _{PLH} , t _{PHL}
74HCT132	3.0 V	6.0 ns	15 pF, 50 pF	t _{PLH} , t _{PHL}

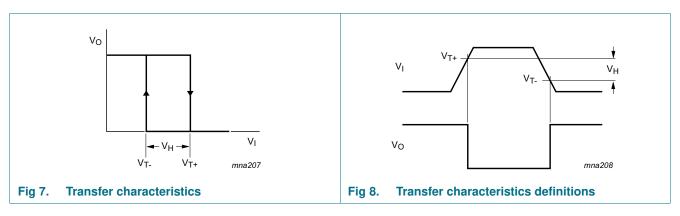
13. Transfer characteristics

Table 10. Transfer characteristics

At recommended operating conditions; voltages are referenced to GND (ground = 0 V); see Figure 7 and Figure 8.

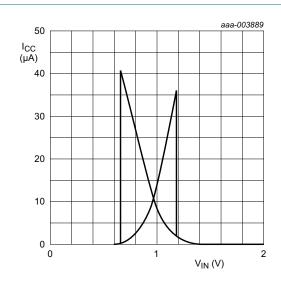
Symbol	Parameter	Conditions	Tai	_{mb} = 25	°C		: –40 °C 85 °C	T _{amb} =	Unit	
			Min	Тур	Max	Min	Max	Min	Max	
74HC132	2							1		
V_{T+}	positive-going	V _{CC} = 2.0 V	0.7	1.18	1.5	0.7	1.5	0.7	1.5	V
	threshold	V _{CC} = 4.5 V	1.7	2.38	3.15	1.7	3.15	1.7	3.15	V
	voltage	V _{CC} = 6.0 V	2.1	3.14	4.2	2.1	4.2	2.1	4.2	V
V_{T-}	negative-going	V _{CC} = 2.0 V	0.3	0.63	1.0	0.3	1.0	0.3	1.0	V
	threshold voltage	V _{CC} = 4.5 V	0.9	1.67	2.2	0.9	2.2	0.9	2.2	V
	voitage	V _{CC} = 6.0 V	1.2	2.26	3.0	1.2	3.0	1.2	3.0	V
V _H	hysteresis	V _{CC} = 2.0 V	0.2	0.55	1.0	0.2	1.0	0.2	1.0	V
	voltage	V _{CC} = 4.5 V	0.4	0.71	1.4	0.4	1.4	0.4	1.4	V
		V _{CC} = 6.0 V	0.6	0.88	1.6	0.6	1.6	0.6	1.6	V
74HCT1	32									
V_{T+}	positive-going	V _{CC} = 4.5 V	1.2	1.41	1.9	1.2	1.9	1.2	1.9	V
	threshold voltage	V _{CC} = 5.5 V	1.4	1.59	2.1	1.4	2.1	1.4	2.1	V
V_{T-}	negative-going	V _{CC} = 4.5 V	0.5	0.85	1.2	0.5	1.2	0.5	1.2	V
	threshold voltage	V _{CC} = 5.5 V	0.6	0.99	1.4	0.6	1.4	0.6	1.4	V
V _H	hysteresis	V _{CC} = 4.5 V	0.4	0.56	-	0.4	-	0.4	-	V
		V _{CC} = 5.5 V	0.4	0.60	-	0.4	-	0.4	-	V

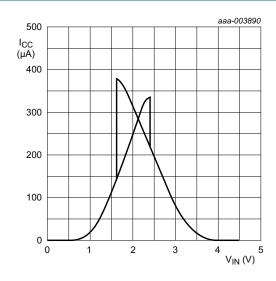
14. Transfer characteristics waveforms



74HC_HCT132

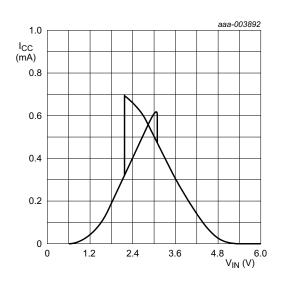
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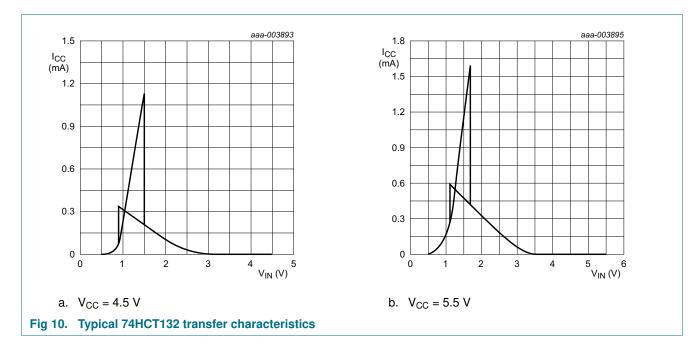
a. $V_{CC} = 2.0 \text{ V}$





c. $V_{CC} = 6.0 \text{ V}$

Fig 9. Typical 74HC132 transfer characteristics



15. Application information

The slow input rise and fall times cause additional power dissipation, this can be calculated using the following formula:

 $P_{add} = f_i \times (t_r \times \Delta I_{CC(AV)} + t_f \times \Delta I_{CC(AV)}) \times V_{CC}$ where:

 P_{add} = additional power dissipation (μW);

 $f_i = input frequency (MHz);$

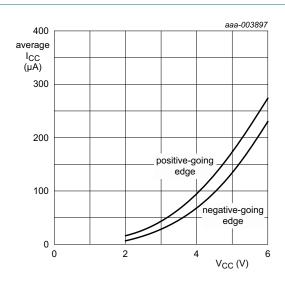
 $t_r = rise time (ns); 10 % to 90 %;$

 $t_f = fall time (ns); 90 \% to 10 \%;$

 $\Delta I_{CC(AV)}$ = average additional supply current (μA).

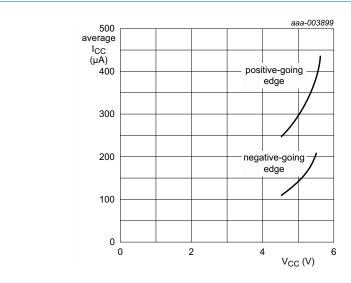
Average $\Delta I_{CC(AV)}$ differs with positive or negative input transitions, as shown in <u>Figure 11</u> and <u>Figure 12</u>.

An example of a relaxation circuit using the 74HC132; 74HCT132 is shown in Figure 13.



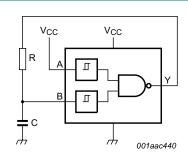
- (1) Positive-going edge.
- (2) Negative-going edge.

Fig 11. Average additional supply current as a function of V_{CC} for 74HC132; linear change of V_I between $0.1V_{CC}$ to $0.9V_{CC}$.



- (1) Positive-going edge.
- (2) Negative-going edge.

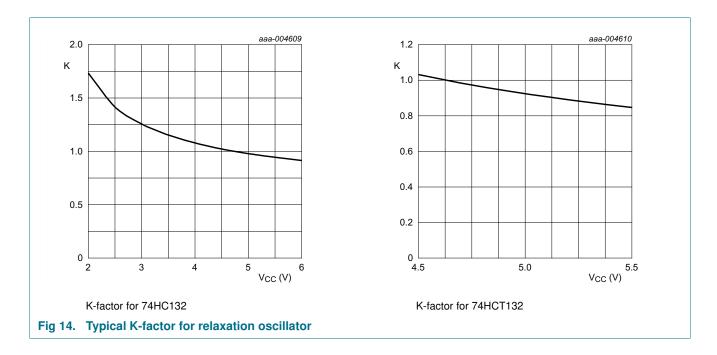
Fig 12. Average additional supply current as a function of V_{CC} for 74HCT132; linear change of V_I between 0.1 V_{CC} to 0.9 V_{CC} .



For 74HC132 and 74HCT132: $f = \frac{1}{T} \approx \frac{1}{K \times RC}$

For K-factor, see Figure 14

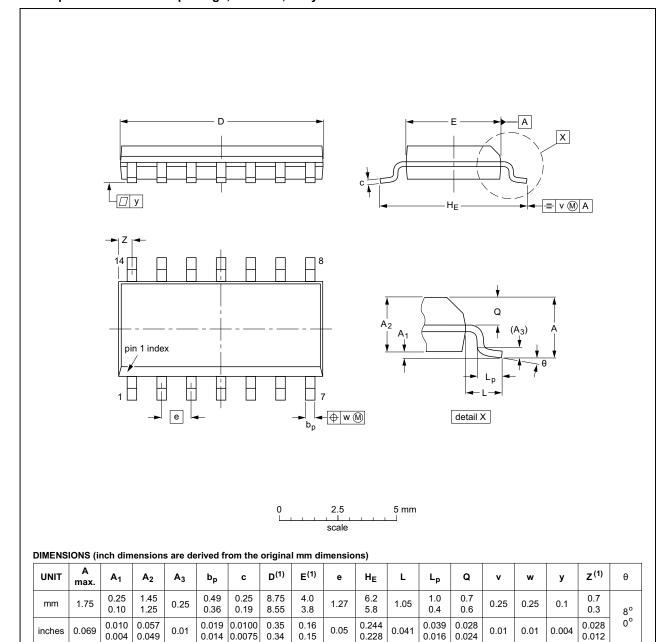
Fig 13. Relaxation oscillator



16. Package outline

SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1



Note

1. Plastic or metal protrusions of 0.15 mm (0.006 inch) maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	JEITA	PROJECTION	ISSUE DATE
SOT108-1	076E06	MS-012			99-12-27 03-02-19

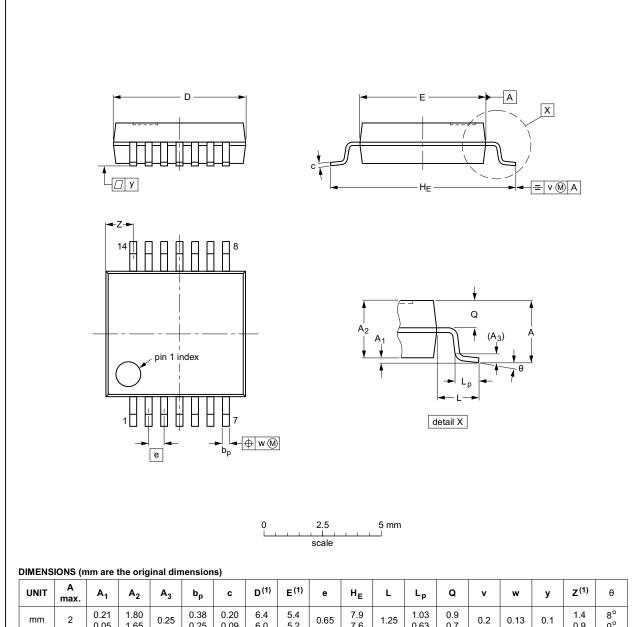
Fig 15. Package outline SOT108-1 (SO14)

74HC_HCT132

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SSOP14: plastic shrink small outline package; 14 leads; body width 5.3 mm

SOT337-1



-							-,												
	UNIT	A max.	A ₁	A ₂	A ₃	b _p	С	D ⁽¹⁾	E ⁽¹⁾	е	HE	L	Lp	Q	v	w	у	Z ⁽¹⁾	θ
	mm	2	0.21 0.05	1.80 1.65	0.25	0.38 0.25	0.20 0.09	6.4 6.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	1.4 0.9	8° 0°

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE
SOT337-1		MO-150				99-12-27 03-02-19

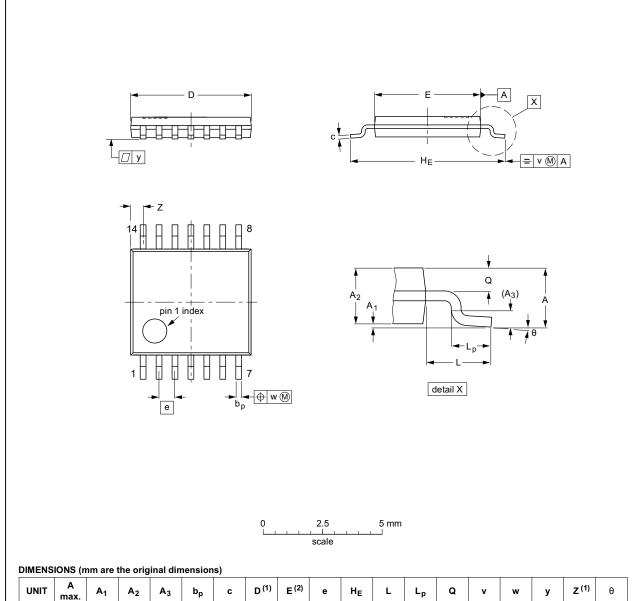
Fig 16. Package outline SOT337-1 (SSOP14)

74HC_HCT132

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TSSOP14: plastic thin shrink small outline package; 14 leads; body width 4.4 mm

SOT402-1



UNIT	A max.	A ₁	A ₂	A ₃	bp	С	D ⁽¹⁾	E (2)	е	HE	L	Lp	Q	v	w	у	Z ⁽¹⁾	θ
mm	1.1	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	5.1 4.9	4.5 4.3	0.65	6.6 6.2	1	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.72 0.38	8° 0°

Notes

- 1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
- 2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE
SOT402-1		MO-153				99-12-27 03-02-18

Fig 17. Package outline SOT402-1 (TSSOP14)

74HC_HCT132

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17. Abbreviations

Table 11. Abbreviations

Acronym	Description
CMOS	Complementary Metal-Oxide Semiconductor
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model
TTL	Transistor-Transistor Logic

18. Revision history

Table 12. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74HC_HCT132 v.4	20151201	Product data sheet	-	74HC_HCT132 v.3
Modifications:	Type numbers 74H0	C132N and 74HCT132N (SOT27-1) removed.	
74HC_HCT132 v.3	20120830	Product data sheet	-	74HC_HCT132_CNV v.2
Modifications:	The format of this da of NXP Semiconduction	•	gned to comply with	the new identity guidelines
	 Legal texts have been 	en adapted to the new co	mpany name where	appropriate.
	 Figure 14 added (type) 	oical K-factor for relaxatio	n oscillator).	
74HC_HCT132_CNV v.2	19970826	Product specification	-	-

19. Legal information

19.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions"
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